

## **Block Diagram**

The functional blocks of this device are shown below:







## <span id="page-1-0"></span>**Pin Assignments**

#### **Figure 3: Optical Module Pinout (Top View) – AS7000-AA**

**Optical Module Pinout:** 

This drawing is not to scale



### **Figure 4: Pin Description**



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## **Absolute Maximum Ratings**

Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in [Electrical Characteristics](#page-5-0) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## **Figure 5: Absolute Maximum Ratings**[\(1\)](#page-4-0)



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## **Note(s):**

<span id="page-4-0"></span>1. All optical customer designs shall be reviewed by **ams** before production.



## <span id="page-5-0"></span>**Electrical Characteristics**

VDD=2.6 to 3.6V, typ. values are at  $T_{AMB}$ =25°C (unless otherwise specified).

All limits are guaranteed. The parameters with min and max values are guaranteed with production tests or SQC (Statistical Quality Control) methods.

**Figure 6: Operating Conditions** 



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#### **Note(s):**

- <span id="page-7-2"></span>1. Deep sleep mode. Use **ams** SDK (software development kit) to enter deep sleep, wakeup with low on GPIO8 pin (if gpio8\_wakeup\_ en=1) or high on GPIO7 (if gpio7\_wakeup\_en=1) or 512Hz oscillator sleep\_timer.
- <span id="page-7-1"></span>2. GPIO0-8 configured to draw minimum current (software dependent).
- <span id="page-7-0"></span>3. Power down mode. Entered by setting enter\_powerdown=1; No oscillator running. Wakeup with low on GPIO8 pin (always) or high on GPIO7 (if gpio7\_wakeup\_en=1).
- <span id="page-7-3"></span>4. A device must internally provide a hold time of at least 300ns for the SDA signal (referred to the V<sub>IHMIN</sub> of the SCL signal) to bridge the undefined region of the falling edge of SCL.
- <span id="page-7-4"></span>5. A fast-mode device can be used in a standard-mode system, but the requirement  $t_{SU:DAT}$  = to 250ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line t<sub>R</sub> max + t<sub>SU:DAT</sub> = 1000 + 250 = 1250ns before the SCL line is released.

#### **Figure 7: I²C Mode Timing Diagram**



**I²C Mode Timing Diagram:** This figure shows the different timings required for I²C communication.

#### **Note(s):**

1. SCL / SDA Programmable to GPIO Pins – See  $1^2C$  Mode.



## **Detailed Description**

## **Optical Analog Front End**

<span id="page-8-0"></span>**Figure 8:**

**Optical Analog Front End – AS7000-AA Configuration** 



#### **Note(s):**

1. Dual Green LED Configuration is shown.

The number of LEDs inside the module depends on the application – [Figure 8](#page-8-0) shows 2 LEDs. If a LED is not populated, the current sink is connected directly to the pin (VD3 and VD4 in above figure).



## *LEDs*

### *AS7000-AA Dual Green LED Configuration*

Two green LEDs are used (pins VD1/VD2). The other two current sinks are available on pins VD3 and VD4.

*LED Characteristics*

**Figure 9: LED Characteristics at T<sub>AMB</sub> = 25°C** 



#### **Note(s):**

<span id="page-9-0"></span>1. The maximum allowed LED current (DC and peak) is specified for 25°C. Lower values apply for higher temperatures.

<span id="page-9-1"></span>2. Add 280mV and use LED current range ≤100mA for designing the VD1/VD2 LED supply (DC-DC converter).

<span id="page-10-1"></span>

## *LED-Driver*

The four LED-driver outputs can be controlled manually or by the built in sequencer. See [Optical Front End Operating Modes](#page-24-0)



### **Figure 10: LED Drivers**

#### **Note(s):**

1. Dual Green LED Configuration.

#### **Figure 11:**

Operating Characteristics of Each LED Current Sink, VDD=3V, T<sub>AMB</sub>=25°C (unless otherwise noted)



#### **Note(s):**

<span id="page-10-0"></span>1. Not production tested. Only guaranteed by lab characterization.



*LED Configuration Registers*

For ledX\_supply\_low registers see register AFE\_PD\_CFG.

**Figure 12: AFE\_LED\_CFG** 



The LED\_CFG register is used to configure the operating mode of the LED outputs.



*AFE\_LED\_CURR Register (Addr: 0x04)* The AFE\_LED\_CURR defines the LED output current.

**Figure 13: AFE\_LED\_CURR Register** 



## <span id="page-13-0"></span>**Figure 14: AFE\_MAN\_SEQ\_CFG**



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## *Photodiode Selection*

In order to have flexible arrangement of the use photodiodes, PD1-PD4 can be individually connected to the photodiode amplifier input. The optional offset current allows cancellation of constant light sources like sunlight. In case of an external photodiode or any other sensor with (low) current output, the pins GPIO6 and GPIO7 can be used as input.

Additionally the sequencer can control the diodes – see diode\_ ctrl described in register AFE\_MAN\_SEQ\_CFG.







## *AFE\_PD\_CFG Register (Addr: 0x08)*

The AFE\_PD\_CFG register is used to configure the input to the photo amplifier.

## **Figure 16: AFE\_PD\_CFG Register**



**Note(s):**

<span id="page-17-0"></span>1. SC\_WS: Self clear, write sets: These registers are reset by the hardware. Set to '1' before using them.



## *Photodiode Characteristics*

#### **Figure 17: Photodiode Arrangement**



#### **Note(s):**

1. Orientation as in [Figure 115](#page-81-0) or [Figure 3.](#page-1-0)

**Figure 18:**

**AS7000-AA Photodiode Sensitivity (Solid Black) and LED Emission Spectrum (Dotted Green) – Dual Green LED Configuration** 



#### **Note(s):**

1. Perpendicular light source.

2. LEDs and Filters are shown for Dual Green LED Configuration.



## **Figure 19:**

Operating Characteristics of Each Photodiode, VDD=3V, T<sub>AMB</sub>=25°C (unless otherwise noted)



#### **Note(s):**

1. For monochromatic light of 555nm, one lux corresponds to 0.146 μW/cm2. That is, one obtains 6.5 lux per μW/cm2



## *Photodiode Trans-Impedance Amplifier (TIA)*

The photodiode amplifier can be configured in three different modes:

- **•** Photocurrent to frequency converter
- **•** Photocurrent to voltage converter
- **•** Photocurrent integrator



**Figure 20: Trans-Impedance-Amplifier (TIA)** 

> The integration time  $t_{INT}$  is defined either by the sequencer (man\_mode=0) of manually through the bit sw\_itg if man\_mode=1.

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## **Figure 21: Settings for the Programming of the TIA**



#### **Note(s):**

1. pd1234 … number of active photodiodes (for example, pd1=1, pd2=0, pd3=1, pd4=0 -> pd1234=2)



## *AFE\_PD\_AMPCFG Register (Addr: 0x0c)*

The AFE\_PD\_AMPCFG register is used to configure the operating mode of the photo-amplifier

**Figure 22: AFE\_PD\_AMPCFG Register** 

Addr: 0x0c		AFE PD AMPCFG		
<b>Bit</b>	<b>Bit Name</b>	<b>Default</b>	<b>Access</b>	<b>Description</b>
31	pd_amp_en	$\Omega$	R/W	0 Activates power down mode of photo-amplifier 1Enables photo-amplifier
13:10	pd_amp_vo	15	R/W	Opamp offset. Use ams device drivers - these automatically configure this register.
9:8	$pd_{-}$ ampcomp	3	R/W	Opamp compensation. Use ams device drivers - these automatically configure this register.
7:5	pd_ampres	0x0	R/W	Feedback resistor 000No resistor in feedback of amplifier 0011MO $0102M\Omega$ $0113M\Omega$ $1005M\Omega$ $1017M\Omega$ $11010M\Omega$ $11115M\Omega$
4:0	pd_ampcap	0x0	R/W	Feedback capacitor - automatically set by ams device drivers for modes using pd_ampres not 000b. Capacitor = $pd$ ampcap*0.1pF

For registers man\_mode and man\_sw\_itg see [AFE\\_MAN\\_SEQ\\_](#page-13-0) [CFG](#page-13-0) .



## *Voltage Mode of the Photodiode Amplifier*

The output voltage of the photodiode amplifier is depending on the feedback component:

**(EQ1)** Feedback resistor: 
$$
U_{out} = I_{photo} \cdot R_{fb}
$$

feedback.

(EQ2) **Feedback capacitor:** 
$$
U_{out} = I_{photo} \cdot \frac{t_{INT}}{C_{fb}}
$$

**Note(s):** The integration time t<sub>INT</sub> is defined either by the sequencer (man\_mode=0) of manually through the bit sw\_itg if man\_mode=1. For the synchronous demodulator only use the resistive

**Figure 23: Difference Between Resistive and Capacitive Feedback** 



<span id="page-24-0"></span>

## **Optical Front End Operating Modes**

Once the photodiode amplifier is configured the measurement can be done in two different ways. Either the LED-outputs, the photodiode amplifier and the ADC are controlled manually by means of register bits, or they are controlled by a built in sequencer.

## *Manual Operation of The Optical Frontend:*

The optical front end can be manually controlled via the AFE\_ MAN\_SEQ\_CFG register using man\_mode=1.

**Figure 24: Manual Operation of the Optical Frontend and LED** 



#### **Note(s):**

1. Applies only if man\_mode=1.

For manual operation of the LEDs and its current sinks see [LED-Driver](#page-10-1).



## *Sequencer*

In order to synchronize the LED-currents, the integration time and the ADC-sampling time, a built in sampling Sequencers can be used. The sequencer generates the 16 bit-timings based on a 1μs clock. The results of the analog to digital conversion are automatically stored in a pipeline buffer or in register adc\_data.

The timings can be programmed with following registers (apply for man\_mode=0):

## **Figure 25: Sequencer Control Registers Overview**



#### **Note(s):**

1. The lowest data value of all registers except seq\_count, seq\_div, seq\_adc\_inc, seq\_adc\_inc\_fract and seq\_adc\_fract is 1.



## **Figure 26: Block Diagram of Sequencer**





## *Sequencer Registers*

For registers man\_mode, man\_sw\_sdmult, man\_sw\_sdpol, man\_sw\_itg, man\_sw\_led4, man\_sw\_led3, man\_sw\_led2, man\_sw\_led1, diode\_ctrl, dma\_disable, led4\_mode, led3\_ mode, led2\_mode and led1\_mode,seq\_en see [AFE\\_MAN\\_SEQ\\_CFG](#page-13-0) .

For register sd\_subs see [AFE\\_SC\\_CFG](#page-39-0) .

*AFE\_SEQ\_DIV\_CNT Register (Addr: 0x24)*

The AFE\_SEQ\_DIV\_CNT register sets the input divider for the main clock.

**Figure 27: AFE\_SEQ\_DIV\_CNT Register** 



### *AFE\_SEQ\_START Register (Addr: 0x28)*

In AFE\_SEQ\_START register the configured sequencer can be started.

**Figure 28: AFE\_SEQ\_START Register** 





#### *AFE\_SEQ\_PER Register (Addr: 0x2C)*

The AFE\_SEQ\_PER register sets one measurement cycle of the sequencer.

**Figure 29: AFE\_SEQ\_PER Register** 



#### *AFE\_SEQ\_LED Register (Addr: 0x30)*

The AFE\_SEQ\_LED register sets the LED drive timing. Data is stored as 16-bit value

**Figure 30: AFE\_SEQ\_LED Register** 



### *AFE\_SEQ\_ITG Register (Addr: 0x34)*

The AFE\_SEQ\_ITG register sets the photoamplifier integration time if using capacitive feedback respectively removes the short of the resistive feedback. Data is stored as 16-bit value

**Figure 31: AFE\_SEQ\_ITG Register** 





### *AFE\_SEQ\_SDP Register (Addr: 0x38)*

The AFE\_SEQ\_SDP register sets the synchronous demodulator positive multiplication time. Data is stored as 16-bit value

**Figure 32: AFE\_SEQ\_SDP Register** 



## *AFE\_SEQ\_SDM1 Register (Addr: 0x3C)*

The AFE\_SEQ\_SDM1 register sets the synchronous demodulator negative multiplication time 1. Data is stored as 16-bit value

**Figure 33: AFE\_SEQ\_SDM1 Register** 



#### *AFE\_SEQ\_SDM2 Register (Addr: 0x40)*

The AFE\_SEQ\_SDM2 register sets the synchronous demodulator negative multiplication time 2. Data is stored as 16-bit value

**Figure 34: AFE\_SEQ\_SDM2 Register** 



#### *AFE\_SEQ\_ADC Register (Addr: 0x44)*

The AFE\_SEQ\_ADC register defines the time when the ADC starts sampling during each measurement cycle. The fraction setting permits a definition of the sampling point as a 1/16 fraction of a sequencer cycle. If seq\_div=0 (1us sequencer clock), then one unit is equivalent to 62.5ns. If, e.g. seq\_div=4 (5us) then the resolution of the fract register is 62.5ns\*5=312.5ns

**Figure 35: AFE\_SEQ\_ADC Register** 



### *AFE\_SEQ\_COUNTER Register (Addr: 0x80)*

The AFE\_SEQ\_COUNTER register shows the counter value of the sequence counter and period counter

**Figure 36: AFE\_SEQ\_COUNTER Register** 





*AFE\_ADC\_COUNTER Register (Addr: 0x84)*

The AFE\_ADC\_COUNTER register shows the current value of the ADC counter

**Figure 37: AFE\_ADC\_COUNTER Register** 



## *Example Sequencer Configurations*

Used adc\_clock = 0 and adc\_highres=0 for the examples to shorten the ADC settling time. As seq\_div = 1 and seq\_ period=40, one sequence is 80μs.

#### *Example 1*

Making 4 measurements with LED1 only.

Integration time is 20 cycles. LED is turned on 10 cycles before integration starts to avoid current bouncing errors.

**Figure 38: Sequencer Example 1** 



**Figure 39:**

**Sequencer Example 1 Waveform** 





Making 4 measurements with LED2 only.

Integration time is 20 cycles. LED is turned ON 10 cycles before integration starts to avoid current bouncing errors.

**Figure 40: Sequencer Example 2** 



#### **Figure 41: Sequencer Example 2 Waveform**





Making 4 measurements, switching between LED1 and LED2.

Integration time is 20 cycles. LED is turned ON 10 cycles before integration starts to avoid current bouncing errors.

**Figure 42: Sequencer Example 3** 



### **Figure 43: Sequencer Example 3 Waveform**





Making 4 measurements, switching LED1 and LED2 simultaneously.

Integration time is 20 cycles. LED is turned ON 10 cycles before integration starts to avoid current bouncing errors.

**Figure 44: Sequencer Example 4** 



**Figure 45:**

**Sequencer Example 4 Waveform** 





Making 4 measurements with LED1 only and subsampling.

Integration time is 20 cycles. LED is turned ON 10 cycles before integration starts to avoid current bouncing errors. ADC sampling starts 5 cycles delayed every measurement.

**Figure 46: Sequencer Example 5** 



**Figure 47:**

**Sequencer Example 5 Waveform** 


### *Example 6*

Making 4 measurements with LED1 only and subsampling.

Integration time is 20 cycles. LED is turned OFF 10 cycles before integration starts to measure fluorescent response of a sensor. ADC sampling starts 5 cycles delayed every measurement.

**Figure 48: Sequencer Example 6** 



**Figure 49:**

**Sequencer Example 6 Waveform** 





## *Example 7*

Making 8 measurements with LED1 only. Reduced cycle time to 40μs.

Integration time is 5 cycles. LED is turned ON 5 cycles before integration starts to avoid current bouncing errors.

**Figure 50: Sequencer Example 7** 



**Figure 51:**

**Sequencer Example 7 Waveform** 





## **Optical Signal Conditioning**





### *Synchronous Demodulator*

An optional synchronous demodulator can be used to detect small optical signals in the presence of large unwanted noise (ambient light). Since the detector synchronizes to the LED frequency, the demodulator can only be used of the measurement sequencer is running.

It includes input filer (high pass at 200Hz, adjustable low pass) and an 2nd order adjustable output low pass. The demodulator itself multiplies the signal by +1 / 0 / -1 with a timing which is controlled by the sequencer.

**Note(s):** The optical signal conditioning stage need sigref\_ en=1 for operation.

### *High Pass Filter*

An optional high pass filter can be used to remove unwanted DC-components from the signal and allows further amplification. In order to guarantee fast settling times of the filter, four cutoff frequencies can be chosen.

### *Gain Stage*

An optional gain stage can be used to amplify the signal after the DC-component has been removed.



## *Optical Signal Conditioning Registers*

Register bit sigref\_en see register [AFE\\_LED\\_CFG.](#page-11-0)





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## *Sync Demodulator Example*

LED1 and LED2 should be modulated with 2kHz

Demodulated signal should be sampled with 20Hz for 1 second.

Calculation of sequencer values:

- 1. Modulation Frequency = 2kHz. Period = 500us.
- 2. Set sequencer period to 250us. -> seq\_div=0, seq\_period=500
- 3. Operation of LEDs between 0us and 100us (depends on LED and Amp-settings)  $\rightarrow$  seq\_led\_start=1, seq\_led\_stop=100
- 4. Operation of photo-amplifier and synchronous demodulator multipl. by +1 between 50us and 100us  $\rightarrow$  seq\_sdp\_start=50, seq\_sdp\_stop=100
- 5. Operation of photo-amplifier and synchronous demodulator multipl. by -1 between 300us and 350us  $\rightarrow$  seq\_sdm1\_start=300, seq\_sdm1\_stop=350
- 6. Sampling position at 495us + settling  $\rightarrow$  seq\_adc=490
- 7. ADC should only sample at 20Hz (50ms). This means sampling at every 50ms/500us = 100th sequencer run. sd\_subs=100
- 8. ADC values should be stored for 1 second. This means 1s/50ms = 20 samples must be stored. ->seq\_count=20



## **Figure 54:**

**Sync Demodulator Example Detail** 



### **Figure 55: Sync Demodulator Example**







## **Electrical Analog Front End**

The electrical analog front end consists of three identical signal paths with independent settings of bias condition, gain and offset.

<span id="page-44-0"></span>**Figure 56: Electrical Analog Front End Internal Circuit** 



#### **Note(s):**

1. Resistor / T-gates resistance values are given as indication – do not rely on absolute values

#### *Input Pins*

Five general purpose pins can be used either as configurable GPIO for the processor or as analog input pins for the electrical analog front end. The analog inputs can be configured to setup different amplifier topologies.

## *AFE Registers*

**Figure 57: AFE\_LED\_CFG** 



**Figure 58: AFE\_EAF** 



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The AFE\_EAF register is used to configure the electrical frontend

**Figure 59: AFE\_EAF\_DAC** 



The AFE\_EAF\_DAC register is used to configure the dac value



## *Possible Configurations of Every Amplifier Stage*

**Figure 60:**

**Non Inverting Amplifier With Offset and Input Voltage Divider (Temperature Sensor)** 



#### **Figure 61:**

**Non Inverting Amplifier With Current Source and Offset (Temperature Sensor)** 



## **Figure 62:**

**Non Inverting Amplifier With Current Source and Reference Path (Temperature Sensor)** 



### **Figure 63: Non Inverting Amplifier High Impedance, GND Referenced**





### **Figure 64: Non Inverting Amplifier With DC-Blocking, Referenced to V\_ADCRef/2**



#### **Figure 65:**

**Non Inverting Amplifier With DC-Blocking and Fast Settling Time, Referenced to ADCRef /2** 



## **ADC**

The ADC is a 14bit successive-approximation register (SAR) type. It supports 12 bit with very fast conversion time up to 1Msps and 14bit with moderate conversion time up to 250ksps.

The ADC is started by the sequencer and its timing or in manual mode (man\_mode=1) by setting seq\_start=1 (seq\_start stays '1' as long as the conversion runs). The AS7000 can be configured to trigger an interrupt upon end of conversion.

**Figure 66: ADC Internal Circuit and Multiplexer** 



For best accuracy the ADC needs to recalibrate itself – use **ams** SDK to initiate the calibration procedure.



**Figure 67:**

Operating Characteristics of the ADC, VDD=3V, T<sub>AMB</sub>=25°C (unless otherwise noted)



**Figure 68:**

**ADC Output Codes (12 Bit Resolution Setting Range)** 

#### **ADC Output Codes:**

For 14 bit resolution the output data range is 0 to 16383, one LSB represents Vref/16384.





## *ADC Registers*

### **Figure 69: AFE\_ADC\_DATA**



The ADC\_DATA register shows the current raw output of the ADC.

**Figure 70: AFE\_ADC\_CFG** 



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## **Power Management and Operating Modes**

After the supply (VDD) is asserted the AS7000 automatically starts up. It is up to the application software into which operating mode the AS7000 is changed (e.g. to power down mode).

The AS7000 can operate in following modes:

**Figure 71: AS7000 Operating Modes** 



#### **Note(s):**

<span id="page-59-0"></span>1. Wakeup by GPIO7=high if gpio7\_wakeup\_en=1; applies for power down and deep sleep mode.

<span id="page-59-1"></span>2. Wakeup by GPIO8=low if gpio8\_wakeup\_en=1.

<span id="page-59-2"></span>3. In power down mode the AS7000 will always wakeup if GPIO8=low independent of previous setting of gpio8\_wakeup\_en.



For operation of the sequencer the 16MHz oscillator is required, therefore the sequencer only operates in active or wait for interrupt mode.

### *Clock Control Unit (CCU) for Peripheral Blocks*

All peripheral block have a reset bit and a clock enable bit. The purpose of these register bits is to disable clock to them when they are not used and therefore reduce power consumption.

**Note(s):** Access to the register is not possible if the clock to the peripheral is disabled or reset is asserted.

e.g. to access any register of AFE (like optical analog front end) set the register bits afe resetn=1 and afe enable=1.

### *Wake-Up From Power Down Mode*

**Figure 72: Wake-Up Logic From Power Down Mode** 





### *Power Management And Operating Modes Registers*

In order to operate the different blocks inside the AS7000, the block has to be enabled (e.g. gpio\_enable=1) and the reset de-asserted (e.g. gpio\_resetn=1).

**Figure 73: CCU\_DEVICEID** 



**Figure 74: CCU\_GPIO** 



**Figure 75: CCU\_I2CM** 





### **Figure 76: CCU\_I2CS**



**Figure 77: CCU\_UART** 



**Figure 78: CCU\_TMR** 



**Figure 79: CCU\_AFE** 



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### **Figure 80: CCU\_WD\_CTRL**



**Figure 81: CCU\_WD\_STATUS** 



**Figure 82: CCU\_WD\_VAL** 



**Figure 83: CCU\_WD\_IRQVAL** 





#### **Figure 84: CCU\_LP\_CFG**



The CCU\_LP registers controls the low power modes

**Figure 85: CCU\_LP\_CTRL** 

![](_page_64_Picture_153.jpeg)

### **Note(s):**

<span id="page-64-0"></span>1. Only use **ams** SDK to enter deep sleep mode, do not set bit directly.

![](_page_65_Picture_1.jpeg)

## **MCU**

The MCU is a 32-bit ARM Cortex-M0-based RISC processor with 32kB of EEPROM memory and 4kB of RAM data memory. Details of the core processor can be found under [infocenter.arm.com.](http://infocenter.arm.com.)

The MCU offers the following features:

- **•** System:
	- ARM Cortex M0 processor with single cycle 32 bit multiplication instruction
	- System tick timer
	- Hardware protection to disable the read or read/write of the internal EEPROM and SRAM
	- Unique ID for every device delivered
- **•** Memory:
	- 32kByte EEPROM memory
	- 4kByte RAM
- **•** Peripherals:
	- 9 general-purpose (GPIO) pins with configurable output structure
	- UART
	- $\cdot$  I<sup>2</sup>C Master
	- $\cdot$  I<sup>2</sup>C Slave
	- 14 bit ADC
	- Watchdog timer
	- 2 general purpose 16 bit timer
- **•** Clock:
	- Internal 16MHz RC oscillator
	- Internal 512Hz watchdog oscillator and timer
- **•** Debug:
	- Serial wire Debug
- **•** Power control:
	- Reduced power modes Sleep, Stop
	- Power ON reset

![](_page_66_Picture_0.jpeg)

### **Figure 86: CPU Internal Block Diagram**

![](_page_66_Figure_3.jpeg)

**ams** delivers a SDK (Software Development Kit) for easy access of the internal digital and analog blocks. The SDK includes detailed documentation of the hardware (like I<sup>2</sup>C, UART) and includes low level drivers.

For accessing of the peripheral registers, a base address needs to added. The base address depends on the block used (see also **ams** provided SDK – software development kit).

![](_page_66_Picture_166.jpeg)

![](_page_67_Picture_1.jpeg)

*Debug – SWD*

<span id="page-67-0"></span>![](_page_67_Figure_3.jpeg)

![](_page_67_Figure_4.jpeg)

#### **Note(s):**

1. Press debug button on power-up (VDD ON).

During power up of the AS7000 the device checks if the pin SIGREF is shorted to GND (e.g. by a resistance of  $10\Omega$ ) – see [Figure 87.](#page-67-0) If this condition is detected and the security bit is not set, a monitor mode is entered.

In this monitor mode the AS7000 waits 5s where a debugger can be connected. If the 10s expires without a debugger connected, the AS7000 continues startup.

If a debugger is connected, the debugger can control AS7000 as required.

**Note(s):** If the security bit is set inside the EEPROM the debugger is bypassed even if SIGREF is shorted to GND upon startup.

![](_page_68_Picture_0.jpeg)

## *GPIO Pins and Output Switch Matrix*

A flexible output switch matrix allows dynamic assignment of the internal digital blocks to the GPIO pins:

![](_page_68_Figure_4.jpeg)

![](_page_68_Figure_5.jpeg)

# **TEST**

### <span id="page-69-0"></span>**Figure 89: Selector Assignments**

![](_page_69_Picture_113.jpeg)

Each of the GPIO pins is capable of adding a pullup and/or pulldown:

![](_page_69_Figure_5.jpeg)

![](_page_69_Figure_6.jpeg)

# **OIMI**

## *I²C Mode*

The AS7000 includes an I<sup>2</sup>C master and slave (independent) hardware block. The pins name SDA and SCL in this section can be mapped during runtime to the GPIO pins according to [Figure 89.](#page-69-0) **ams** SDK operates the I²C slave on GPIO2 (=SDA) and GPIO3 (=SCL) and uses a default I²C address of 0x30 (7-bit format; R/W bit has to be added) respectively 60h (8-bit format for writing) and 61h (8-bit format for reading). It expects external pullup resistors.

*I²C Serial Control Interface*

### **I²C Feature List:**

Fast mode (400kHz) and standard mode (100kHz) support

7+1-bit addressing mode

Write formats: Single-Byte-Write, Page-Write

Read formats: Current-Address-Read, Random-Read, Sequential-Read

SDA input delay and SCL spike filtering by integrated RC-components

### **I²C Protocol**

**Figure 91: I²C Symbol Definition** 

![](_page_70_Picture_145.jpeg)

**I²C Symbol Definition:** Shows the symbols used in the following mode descriptions.

![](_page_71_Picture_1.jpeg)

## **I²C Write Access**

Byte Write and Page Write formats are used to write data to the slave.

![](_page_71_Figure_4.jpeg)

![](_page_71_Figure_5.jpeg)

**I<sup>2</sup>C Byte Write:** Shows the format of an I<sup>2</sup>C byte write access.

#### **Figure 93: I²C Page Write**

![](_page_71_Figure_8.jpeg)

**I²C Page Write:** Shows the format of an I²C page write access.

The transmission begins with the START condition, which is generated by the master when the bus is in IDLE state (the bus is free). The device-write address is followed by the word address. After the word address any number of data bytes can be sent to the slave. The word address is incremented internally, in order to write subsequent data bytes on subsequent address locations.

For reading data from the slave device, the master has to change the transfer direction. This can be done either with a repeated START condition followed by the device-read address, or simply with a new transmission START followed by the device-read address, when the bus is in IDLE state. The device-read address is always followed by the 1st register byte transmitted from the slave. In Read Mode any number of subsequent register bytes can be read from the slave. The word address is incremented internally.


# **I²C Read Access**

Random, Sequential and Current Address Read are used to read data from the slave.





**I²C Random Read:** Shows the format of an I²C random read access.

Random Read and Sequential Read are combined formats. The repeated START condition is used to change the direction after the data transfer from the master.

The word address transfer is initiated with a START condition issued by the master while the bus is idle. The START condition is followed by the device-write address and the word address.

In order to change the data direction a repeated START condition is issued on the 1st SCL pulse after the acknowledge bit of the word address transfer. After the reception of the device-read address, the slave becomes the transmitter. In this state the slave transmits register data located by the previous received word address vector. The master responds to the data byte with a not-acknowledge, and issues a STOP condition on the bus.

#### **Figure 95: I²C Sequential Read**



**I²C Sequential Read:** Shows the format of an I²C sequential read access.



Sequential Read is the extended form of Random Read, as more than one register-data bytes are transferred subsequently. In difference to the Random Read, for a sequential read the transferred register-data bytes are responded by an acknowledge from the master. The number of data bytes transferred in one sequence is unlimited (consider the behavior of the word-address counter). To terminate the transmission the master has to send a not-acknowledge following the last data byte and generate the STOP condition subsequently.

# **Figure 96: I²C Current Address Read**



**I<sup>2</sup>C Current Address Read:** Shows the format of an I<sup>2</sup>C current address read access.

To keep the access time as small as possible, this format allows a read access without the word address transfer in advance to the data transfer. The bus is idle and the master issues a START condition followed by the Device-Read address. Analogous to Random Read, a single byte transfer is terminated with a not-acknowledge after the 1st register byte. Analogous to Sequential Read an unlimited number of data bytes can be transferred, where the data bytes has to be responded with an acknowledge from the master. For termination of the transmission the master sends a not-acknowledge following the last data byte and a subsequent STOP condition.



# *GPIO, SWD and Security Registers*

<span id="page-74-1"></span>**Figure 97: GPIO\_DATA** 



#### **Note(s):**

<span id="page-74-0"></span>1. The upper 4 bits are routed to the LED pins. This way the software can output data conveniently and quickly. The AFE module has to be turned ON and the LED have to be enabled for this to work.

**Figure 98: GPIO\_OE** 



**Figure 99: GPIO\_WMASK** 



# **am**

# **Figure 100: GPIO\_INTTYPE**



**Figure 101: GPIO\_INTPOL** 



**Figure 102: GPIO\_STATUS** 



**Figure 103: GPIO\_INTMASK** 





# **Figure 104: GPIO\_INTR**



**Figure 105: GPIO\_D\_SET** 



**Figure 106: GPIO\_OE\_SET** 



**Figure 107: GPIO\_D\_CLR** 



#### **Figure 108: GPIO\_OE\_CLR**



**Figure 109: CCU\_IOFUNC0** 



**amin** 

# <span id="page-78-0"></span>**amin**

# The CCU\_IOFUNC0/1/2 gpioX\_func register defines the multiplexing mode of each pin.

**Figure 110: gpioX\_func Codings (X=0…8)** 



# The CCU\_IOFUNC0/1/2 gpioX\_pd fields define the pullup/pulldown configuration

<span id="page-78-1"></span>**Figure 111: gpioX\_pd Codings (X=0…8)** 



# **amin**

# **Figure 112: CCU\_IOFUNC1**



# **Figure 113: CCU\_IOFUNC2**







#### **Figure 114: CCU\_RETENTION**



The CCU\_RETENTION register is the only register that is not affected by powerdown, Only a power cycle will reset these bits.



# <span id="page-81-0"></span>**Application Information**

The AS7000 has a built-in I²C master and host device. Therefore it allows to connect an accelerometer used for motion artefact compensation in two ways:

- 1. Connected through the host and data provided by the host to the AS7000 via the AS7000 I²C slave
- 2. Connected directly to the AS7000 and the AS7000 I²C master retrieves the data from the accelerometer.

Following two figures show the different configurations.

**Figure 115: Measurement System With Motion Artefact Compensation** 



#### **Note(s):**

1. Accelerometer data provided by host.

In above configuration the host needs to send the accelerometer data to the AS7000 via the I²C interface.

# NITI

# **Figure 116:**

**Measurement System With Motion Artefact Compensation Using AS7000 Dedicated Accelerometer** 



# **Note(s):**

1. Accelerometer connected directly

In above configuration, the AS7000 I²C master is used to poll the data from the accelerometer.

The AS7000 has internal protection diodes on all GPIO pins connected to VDD. If VDD is switched off, all GPIO pins are clamped to this VDD supply plus one diode voltage (typically 0.6V). Therefore connect the periphery supply of these pins (example: I²C pins from host in above example connected to GPIO2/3), which are connected to the AS7000 GPIO pins to the same VDD supply as the AS7000. If this is not possible, ensure that these pins are at logic 0 if the VDD supply of AS7000 is switched off.



Due to the integration of the optical diode / optical frontend / analog processing / ADC and microprocessor a heart-rate measurement application can be built with very small PCB area as shown in following figure:

# **Figure 117:**

**Typical Form Factor Including VDD LDO** 



# *External Components*

<span id="page-83-0"></span>**Figure 118: External Components** 





# <span id="page-84-0"></span>**Package Drawings & Markings**

**Figure 119: Package Drawings** 



#### **Note(s):**

1. **XXXXX** - Tracecode backside marking (upside down)

# <span id="page-85-1"></span>**Ordering & Contact Information**

**Figure 120: Ordering Information** 



**Note(s):**

<span id="page-85-0"></span>1. **XXXXX** - Tracecode backside marking

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# <span id="page-88-0"></span>**Document Status**



# <span id="page-89-0"></span>**Revision Information**



# **Note(s):**

1. Page and figure numbers for the previous version may differ from page and figure numbers in the current revision.

2. Correction of typographical errors is not explicitly mentioned.





# **Content Guide**

- **[1 General Description](#page--1-0)**
- [1 Key Benefits and Features](#page--1-1)
- [1 Applications](#page--1-2)
- [2 Block Diagram](#page-0-0)
- **[3 Pin Assignments](#page-1-0)**
- **[5 Absolute Maximum Ratings](#page-3-1)**
- **[7 Electrical Characteristics](#page-5-0)**

# **[10 Detailed Description](#page-8-0)**

- [10 Optical Analog Front End](#page-8-1)
- [11 LEDs](#page-9-0)
- [12 LED-Driver](#page-10-0)
- [18 Photodiode Selection](#page-16-0)
- [20 Photodiode Characteristics](#page-18-0)
- [22 Photodiode Trans-Impedance Amplifier \(TIA\)](#page-20-0)
- [25 Voltage Mode of the Photodiode Amplifier](#page-23-0)

#### [26 Optical Front End Operating Modes](#page-24-0)

- [26 Manual Operation of The Optical Frontend:](#page-24-1)
- [27 Sequencer](#page-25-0)
- [29 Sequencer Registers](#page-27-0)
- [33 Example Sequencer Configurations](#page-31-0)

# [40 Optical Signal Conditioning](#page-38-0)

- [40 Synchronous Demodulator](#page-38-1)
- [40 High Pass Filter](#page-38-2)
- [40 Gain Stage](#page-38-3)
- [41 Optical Signal Conditioning Registers](#page-39-0)
- [43 Sync Demodulator Example](#page-41-0)

# [46 Electrical Analog Front End](#page-44-0)

- [46 Input Pins](#page-44-1)
- [47 AFE Registers](#page-45-0)
- [51 Possible Configurations of Every Amplifier Stage](#page-49-0)
- [54 ADC](#page-52-0)
- [56 ADC Registers](#page-54-0)

#### [61 Power Management and Operating Modes](#page-59-0)

- [62 Clock Control Unit \(CCU\) for Peripheral Blocks](#page-60-0)
- [62 Wake-Up From Power Down Mode](#page-60-1)
- [63 Power Management And Operating Modes Registers](#page-61-0)
- [67 MCU](#page-65-0)
- [69 Debug SWD](#page-67-0)
- [70 GPIO Pins and Output Switch Matrix](#page-68-0)
- [72 I²C Mode](#page-70-0)
- [76 GPIO, SWD and Security Registers](#page-74-1)

#### **[83 Application Information](#page-81-0)**

- [85 External Components](#page-83-0)
- **[86 Package Drawings & Markings](#page-84-0)**
- **[87 Ordering & Contact Information](#page-85-1)**
- **[88 RoHS Compliant & ams Green Statement](#page-86-0)**
- **[89 Copyrights & Disclaimer](#page-87-0)**
- **[90 Document Status](#page-88-0)**
- **[91 Revision Information](#page-89-0)**

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